			-40°C TO + 85°C (NOTE	STOR 1) RANG		IPERATURE	-10°C TO + 60°C(№	NOTE 3))
	TEMPERATURE RANGE			STOR					
	HUMIDITY RA	NGE	40% T0 + 80% (NOTE	-		GE ONNECTOR	40% T0 + 70% (N0)		
	CURRENT		250V AC/DC AWG24 : 2,5A				DF11-**DS-2C(.##)	
	CORRENT					ADEE			
			AWG26 : 2.0A AWG28 : 1.0A				AWG24 TO 28		
-1	ТЕМ		TEST METHOD			REOL	JIREMENTS	QT	A
			TEOT METHOD			n L Q			
GENERAL EX		VISUALLY	AND BY MEASURING INSTRU	JMENT.	ACCOR	DING TO DRA	WING.	X	2
MARKING		CONFIRM	ED VISUALLY.					Х	
ELECTR	IC CHARA	CTERIS	STICS						
CONTACT RE	ESISTANCE	100mA (D	C OR 1000 Hz).		30mΩ	MAX.		Х	-
								~	
			INSERTIONS AND EXTRACT	IONS	① CON	ITACT RESIST	ANCE: 30mΩ MAX.		Т
					② NO DAMAGE, CRACK OR LOOSENESS OF			x	
					PAF			^	-
CONTACT INSERTION		□0.5±0.002 BY STEEL GAUGE.			INSERTION FORCE 4.4N MAX EXTRACTION FORCE 0.3N MIN			x	
VIBRATION		FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE					DISCONTINUITY OF 1µs.		+
		0.75 mm, AT 2 h, FOR 3 DIRECTIONS.			-	2 NO DAMAGE, CRACK OR LOOSENESS OF			-
SHOCK		490 m/s ² DURATION OF PULSE 11 ms AT 3 TIMES FOR 3				PARTS. ① NO ELECTRICAL DISCONTINUITY OF 1μs.			+
		DIRECTIONS.			② NO I	DAMAGE, CRA	CK OR LOOSENESS OF	Х	-
					PAF	TS.			
RAPID CHAN			TURE -55 \rightarrow 5 TO 35 \rightarrow 85 \rightarrow 5	5 TO 35 °C	① CON	ITACT RESIST	ANCE: 30mΩ MAX.		Т
TEMPERATURE		TIME $30 \rightarrow 10 \text{ TO } 15 \rightarrow 30 \rightarrow 10 \text{ TO } 15 \text{ min}$			-		CK OR LOOSENESS OF	Х	-
		UNDER 5			PAF				_
DAMP HEAT (STEADY STATE)		EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.			<u> </u>	ITACT RESIST		v	
					(2) NO I	JAIVIAGE, ORA	CK OR LOOSENESS OF	X	
REMARKS NOTE 1:INCL NOTE 2:NO C NOTE 3:APPL	UDING THE TEI CONDENSING. LY TO THE CON	IDITION OF I	E RISE BY CURRENT		PAF CTS BEFC	RTS.) ON PCB,	×	
REMARKS NOTE 1:INCL NOTE 2:NO C NOTE 3:APPL AFTE	UDING THE TEI CONDENSING. LY TO THE CON	IDITION OF I ON PCB, OPE	ONG TERM STORAGE FOR L RATION TEMPERATURE AND		PAF CTS BEFC	RTS.) ON PCB,	*	
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REMARKS NOTE 1:INCL NOTE 2:NO C NOTE 3:APPL AFTE STO	UDING THE TEI CONDENSING. LY TO THE CON ER MOUNTED C RAGE DURING	IDITION OF I DN PCB, OPE TRANSPOR TRANSPOR ESCRIPTIC	ONG TERM STORAGE FOR L RATION TEMPERATURE AND TATION.	D HUMIDITY RAN	CTS BEFC GE IS APP	APPROVED	O ON PCB, TERIM CHECKED SZ. ONO TS. SAKATA	DA 2018 2008	3110 3011
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